

DERWENT-ACC-NO: 1999-596749  
DERWENT-WEEK: 200032  
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TITLE: Bevel surface processing used in semiconductor wafer manufacture - involves polishing bevel surface of semiconductor wafer, to set its surface roughness to specific value

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 11260775 A	September 24, 1999	N/A	004	H01L 021/304

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
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ABSTRACTED-PUB-NO: JP 11260775A

BASIC-ABSTRACT: NOVELTY - Polysilicon film (2) is formed surrounding the semiconductor wafer (1). Polysilicon film in the bevel surface (11) of the semiconductor wafer is removed and polished so that its surface roughness is set to be 400 Angstrom or less.

USE - In semiconductor wafer manufacture.

ADVANTAGE - The bad influence of bevel surface on epitaxial growth or device production process is prevented, by setting its roughness to specific value. Thus, productivity is improved.

DESCRIPTION OF DRAWING - The figure shows partially enlarged sectional view of semiconductor wafer in each process of manufacturing method. (1) Semiconductor wafer; (2) Polysilicon film; (11) Bevel surface.

CHOSEN-DRAWING: Dwg.1/3

TITLE-TERMS:

BEVEL SURFACE PROCESS SEMICONDUCTOR WAFER MANUFACTURE POLISH  
BEVEL SURFACE  
SEMICONDUCTOR WAFER SET SURFACE ROUGH SPECIFIC VALUE

DERWENT-CLASS: L03 U11

CPI-CODES: L04-B04;

**EPI-CODES: U11-C06A1A;**

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